TM 11-6625-2837-14&P-7

TECHNICAL MANUAL

OPERATOR'S, ORGANIZATIONAL, DIRECT SUPPORT,AND GENERAL SUPPORT MAINTENANCE MANUAL INCLUDING REPAIR PARTS AND SPECIAL TOOLS LIST (INCLUDING DEPOT MAINTENANCE REPAIR PARTS AND SPECIAL TOOLS)

FOR

RF SECTION HP-86602B
(NSN 6625-01-031-8853)

HEADQUARTERS, DEPARTMENT OF THE ARMY
OCTOBER 1981

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TECHNICAL MANUAL	)	HEADQUARTERS
	)	DEPARTMENT OF THE ARMY
No. 11-6625-2825-14&p-7	)	Washington, D.C., 18 October 1981

OPERATOR'S, ORGANIZATIONAL, DIRECT SUPPORT AND GENERAL SUPPORT MAINTENANCE MANUAL INCLUDING REPAIR PARTS AND SPECIAL TOOLS LISTS

FOR

RF SECTION PLUG-IN, HEWLETT-PACKARD MODEL 86602B

(NSN 6625-01-031-8853)

CURRENT AS OF 30 JANUARY 1981

REPORTING ERRORS AND RECOMMENDING IMPROVEMENTS

You can help improve this manual. If you find any mistakes or if you know of a way to improve the procedures, please let us know. Mail your letter or DA Form 2028 (Recommended Changes to Publications and Blank Forms), direct to: Commander, US Army Communications and Electronics Materiel Readiness Command, ATTN: DRSEL-ME-MQ, Fort Monmouth, New Jersey 07703. In either case, a reply will be furnished direct to you.

This manual is an authentication of the manufacturer's commercial literature which, through usage, has been found to cover the data required to operate and maintain this equipment. The manual was not prepared in accordance with military specifications; therefore, the format has not been structured to consider categories of maintenance. Section IX contains improvements made after the printing of the manufacturer's manual.

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NOTE

Users of this manual are advised to consult SECTION IX, ERRATA. SECTION IX contains errors and changes in text and illustrations. The user should correct the errors and perform the changes indicated, as needed.

SECTION 0

INTRODUCTION

0-1. Scope

This manual describes RF Section Hewlett-Packard Model 86602B, hereinafter referred to as the RF Section, and provides instructions for its operation and maintenance.

This manual applies directly to instruments with serial numbers prefixed 1638A. It is also applicable to instruments with other serial number prefixes for which manual changes are given in SECTION VII.
SECTION VI includes Table 6-4, a cross reference between the Hewlett-Packard part numbers and the equivalent NATO/NATIONAL Stock Numbers (NSN).
Appendix A provides a reference of pertinent Department of the Army publications.
Appendix B contains the Maintenance Allocation Chart (MAC) which defines the levels and scope of maintenance functions for the equipment in the Army system and a list of the tools and test equipment required.

0-2. Indexes of Publications

a. DA Pam 310-4. Refer to the latest issue of the DA Pam 310-4 to determine whether there are new editions, changes or additional publications pertaining to the equipment.

b. DA Pam 310-7. Refer to DA Pam 310-7 to determine whether there are Modification Work Orders (MWOs) pertaining to the equipment.

0-3. Maintenance Forms, Records and Reports

a. Reports of Maintenance and Unsatisfactory Equipment. Department of the Army forms and procedures used for equipment maintenance will be those prescribed by TM 38-750, the Army Maintenance Management System.

b. Report of Item and Packaging Discrepancies. Fill out and forward SF 364 (Report of Discrepancy (ROD) as prescribed in AR 735-11-2/DLAR 4140.55/NAVSUPINST 4440.127E/AFR 400.54/MCO 4430.E.

c. Discrepancy in Shipment Report (DISREP) (SF 361). Fill out and forward Discrepancy in Shipment Report (DISREP) (SF 361) as prescribed in AR 55-38/NAVSUPINST 4610.33B/AFR 75-18/MCO P4610.19C and DLAR 4500.15.

0-4. Reporting Equipment Improvement Recommendations (EIR)

If your HP 86602B RF Section needs improvement, let us know. Send us an EIR. You, the user, are the only one who can tell us what you don't like about your equipment. Let us know why you don't like the design. Tell us why a procedure is hard to perform. Put it on an SF 368 (Quality Deficiency Report). Mail it to: Commander, US Army Communications - Electronics Command, ATTN: DRSEL-ME-MQ, Fort Monmouth, New Jersey 07703. We'll send you a reply.

0-5. Administrative Storage.

Store in accordance with Paragraphs 2-17 through 2-22.

0-6. Destruction of Army Electronics Materiel

Destruction of Army electronics materiel to prevent enemy use shall be in accordance with TM 750-244-2.

MODEL 86602B

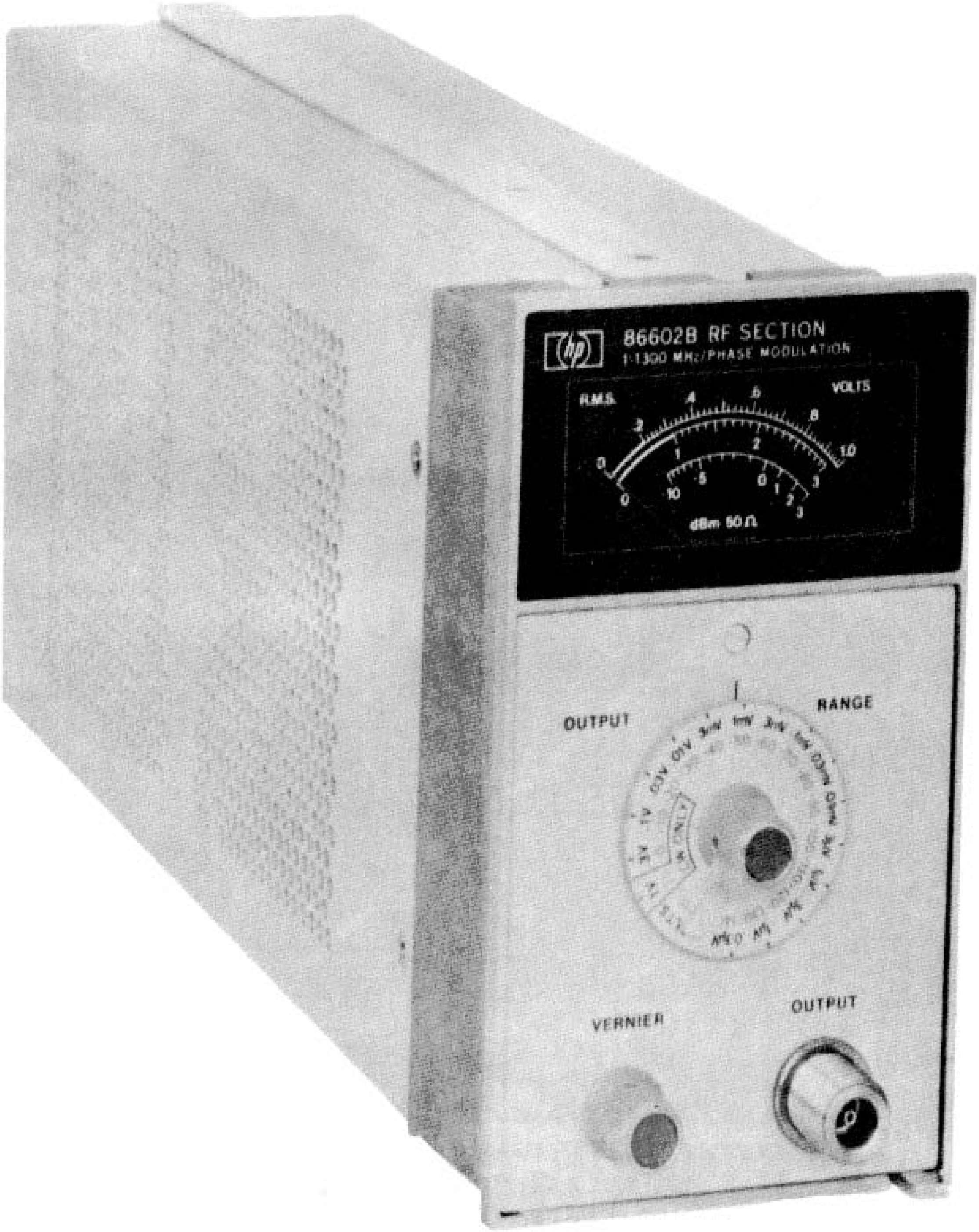

Figure 1-1. HP Model 86602B RF Section (Option 002 Shown)

SECTION I
GENERAL INFORMATION

1-1. INTRODUCTION

1-2. This manual contains all information required to install, operate, test, adjust and service the Hewlett-Packard Model 86602B RF Section plug-in, hereinafter referred to as the RF Section. For information concerning related equipment, such as the Hewlett-Packard Model 8660-series mainframes or the Model 11661 Frequency Extension Module, refer to the appropriate manual or manuals.

1-3. This manual is divided into eight sections which provide information as follows:

a. SECTION I, GENERAL INFORMATION, contains the instrument description and specifications as well as the accessory and recommended test equipment list.

b. SECTION II, INSTALLATION, contains information relative to receiving inspection, preparation for use, mounting, packing, and shipping.

c. SECTION III, OPERATION, contains operating instructions for the instrument.

d. SECTION IV, PERFORMANCE TESTS, contains information required to verify that instrument performance is in accordance with published specifications.

e. SECTION V, ADJUSTMENTS, contains information required to properly adjust and align the instrument after repair.

f. SECTION VI, REPLACEABLE PARTS, contains information required to order all replacement parts and assemblies.

g. SECTION VII, MANUAL CHANGES, provides information to document all serial number prefixes listed on the title page.

h. SECTION VIII, SERVICE, contains descriptions of the circuits, schematic diagrams, parts location diagrams, and troubleshooting procedures to aid the user in maintaining the instrument.

1-4. Figure 1-1 shows the Option 002 RF Section.

1-5. DELETED

1-6. On the title page of this manual, below the manual part number, is a “Microfiche” part number. This number may be used to order 4 x 6-inch microfilm transparencies of the manual. Each microfiche contains up to 60 photo-duplicates of the manual pages. The microfiche package also includes the latest Manual Changes supplement as well as all pertinent Service Notes.

1-7. SPECIFICATIONS

1-8. Instrument specifications are listed in Table 1-1. These specifications are the performance standards, or limits against which the instrument may be tested.

1-9. INSTRUMENTS COVERED BY MANUAL 1-10. This instrument has a two-part serial number. The first four digits and the letter comprise the serial number prefix. The last five digits form the sequential suffix that is unique to each instrument. The contents of this manual apply directly to instruments having the same serial number prefix(es) as listed under SERIAL NUMBERS on the title page.

1-11. For information concerning a serial number prefix not listed on the title page or in the Manual Changes supplement, contact your nearest Hewlett-Packard office.

1-12. MANUAL CHANGE SUPPLEMENTS

1-13. An instrument manufactured after the printing of this manual may have a serial prefix that is not listed on the title page. This unlisted serial